SUSTAINABILITY

RoHS Supplier Self-Certification Form

Company Name	广州腾远信息技术有限公司
Company Address	广州市天河区石牌西路8号楼2110-2111
Manufacturer Part Number(s)	73171122000003
Part Number(s)	73171122000003

Restricted Substances and applicable Maximum Concentration Values (MCV):

1. Lead (Pb) – 1000 PPM
2. Mercury (Hg) – 1000 PPM
3. Cadmium (Cd) – 100 PPM
4. Hexavalent Chromium (Cr6+) – 1000 PPM
5. Polybrominated biphenyls (PBB) – 1000 PPM
6. Polybrominated biphenyl ether (PBDE) – 1000 PPM
7. Bis(2-ethylhexyl) phthalate (DEHP) (0,1 %
8. Butyl benzyl phthalate (BBP) (0,1 %)
9. Dibutyl phthalate (DBP) (0,1 %)
10. Diisobutyl phthalate (DIBP) (0,1 %)

© Copyright 2019 ABB. All rights reserved.

Full Compliance - without Exemptions ☒ (place " x" in box, if appropriate)

We hereby declare that our raw material, production processes and code / codes listed above, have a chemical composition in accordance with the European Union Directive 2011/65/EU, on Restriction of Hazardous Substances (RoHS) and as amended in COMMISSION DELEGATED DIRECTIVE (EU) 2015/863 of 31 March 2015. Specifically, there are none of the substances listed above intentionally added to our listed items and there are no incidental concentrations of these substances above the applicable MCV at the homogeneous level.

Compliance - with Exemptions ☐ (place " x" in box, if appropriate)

We hereby declare that our raw material, production process and code / codes listed above, have a chemical composition in accordance with the European Union Directive 2011/65/EU, on Restriction of Hazardous Substances (RoHS) and as amended in COMMISSION DELEGATED DIRECTIVE (EU) 2015/863 of 31 March 2015. Specifically, there are none of the substances listed above intentionally added to our listed items and there are no incidental concentrations of these substances above the applicable MCV at the homogeneous level with the exception of the below identified exemption(s):

Exemption Number(s) from Appendix A _____

We also declare identified code(s) are made according to our specification and documentation.

Signature	贺慧丹	Date	2022年3月23日
Name	ABB滴股#731711220003	Title	销售经理
E-mail address	1147511145@qq.com	Direct Phone	13828446359

Appendix A – RoHS Exemptions Applicable to our Products.

Exemption Number	Definition	Applicable To
6(a)	Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35 % lead by weight	Sheet metal, screws, washers, nuts, etc.
6(b)	Lead as an alloying element in aluminum containing up to 0.4 % lead by weight	Heatsinks, brackets, O-rings, etc.
6(c)	Copper alloy containing up to 4 % lead by weight	Brass/bronze parts, leadframes, screws, terminals, pins, etc.

© Copyright 2019 ABB. All rights reserved.

7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)	IC die attach, resistor terminations, flip-chip bumps, etc.
7(b)	Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications	Second-level interconnect (component to board) solder for products only to be used in customer servers & network equipment. Non "G" products.
7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezo electronic devices, or in a glass or ceramic matrix compound	Resistor, capacitor, diode terminations and ceramic bodies; IC passivation.
7(c)-II	Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher	Lead, lead oxide, lead dioxide, lead titanate, etc. in dielectric only.
7(c)-III	Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC	Lead, lead oxide, lead dioxide, lead titanate, etc. in dielectric only. This exemption expires on 1 January 2013 and no longer acceptable for our parts.
8(b)	Cadmium and its compounds in electrical contacts	Contact metal for switches, relays, etc.
11(b)	Lead used in other than C-press compliant pin connector systems	Any pin/receptacle connectors This exemption expires on 1 January 2013 and no longer acceptable for our parts
15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages	Flip-chip ICs, usually found in BGA packages, but some flip-chip leadframe packages do exist.

© Copyright 2019 ABB. All rights reserved.